Present: D. Esperante, A. Gallas, P. Rodríguez, J. Saborido, E. Pérez, P. Vázquez, A. Pazos, B. Adeva.

Microscope:

- It is already mounted. All the microscope functionalities have been tested.
- A X-Y table has also been ordered.

VeLo module:

- Bonding of Beetle's control and power lines is done and successfully tested with the Heidelberg´s hybrid-testing box. The Beetle to pitch-adapter is only done for 1 Beetle. Gluing the sensor and PA to sensor bonding is the next step.
- Antonio is building some glass pieces to make the module structure more robust, by gluing together the 2 ceramic plates. He is performing some tests with different epoxies and materials.
- For the sensor bonding Eliseo is waiting for the microscope to make an optimized mapping of the strips to be instrumented.

DEPFET:

- Jevgenij has gone to Bonn with everything installed in his laptop. He will bring back the S3B with him.
- The damaged DEPFETs have been taken to Bonn to test them there.
- The LV is as it was 3 months ago. The idea is to use the same kind of bulk PS as already installed in the Silicon Tracker detector of the Belle experiment. In addition, we will try to copy as much as possible from the S3B system. The design will start soon.

DEPFET analysis:

- The DEPFET analysis software has been installed in Jevgenij's laptop by Carmen and she is also is looking forward to install the ILC software in Grid.

Project shared with USC electronics group:

- We will get news on 29 Sept 2009 about a 3D integration conference.

VeLo upgrade:

- About the technology: TimePix is the first option. The micro-strip option is thought as a backup solution. FPIX option was discarded.
- The micro-strip general purpose telescope construction has been somehow discarded. The idea is to improve the TimePix telescope.

ST:

- Pablo Rodríguez has finalized the tuning of the Beetle parameters for the Inner Tracker. He has to finalize the long pulse-shape scan to analyze the Beetle undershoot.

ST TED runs:

- It is taking place mid-October.

Thinning of 3D silicon sensors at CNM:

- We've bought 15 wafers to build TimePix like sensors. No production date from CNM yet.